



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PCB / CHIP LED
- ▶ 0606 (0.8t)
- ▶ Red (640nm) / Yellow (590nm) / Green (570nm)

NOM11S82



Release Date: 07 August 2014 Version: A1.0



0606 0.8t Series

RoHS
Compliant



FEATURES (Red/Yellow/Green):

- **Package:** PCB / CHIP LED SMT Package
- **Forward Current:** 20/20/20mA*
- **Forward Voltage (typ.):** 2.0/2.0/2.0V
- **Luminous Intensity (typ.):** 60/150/12mcd @20mA
- **Colour:** Red/Yellow/Green
- **Wavelength:** 640/590/570nm
- **Viewing angle:** 140/140/140°
- **Materials:**
 - Die: AlGaInP/AlGaInP/GaP
 - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+80°C
- **Storage Temperature:** -40~+85°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - Wavelength
- **Soldering methods:** Reflow soldering
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** : 8mm tape with 4000/reel, ø180mm (7")

* In the order of Red/Yellow/Green.

APPLICATIONS:

- Indicator
- Dashboard
- 3C Application
- Backlighting
- Decoration Lighting

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

| Parameter | Symbol | Ratings | Unit |
|--------------------------------------|-----------|-------------|---------|
| Forward Current | I_F | 30/30/30* | mA |
| Peak Forward Current Duty 1/10@10KHz | I_{FP} | 125/125/125 | mA |
| Reverse Current @5V | I_R | 10/10/10 | μ A |
| Power Dissipation | P_D | 75/75/75 | mW |
| Operating Temperature | T_{OPR} | -40~+80 | °C |
| Storage Temperature | T_{STG} | -40~+85 | °C |

- * In the order of Red/Yellow/Green.

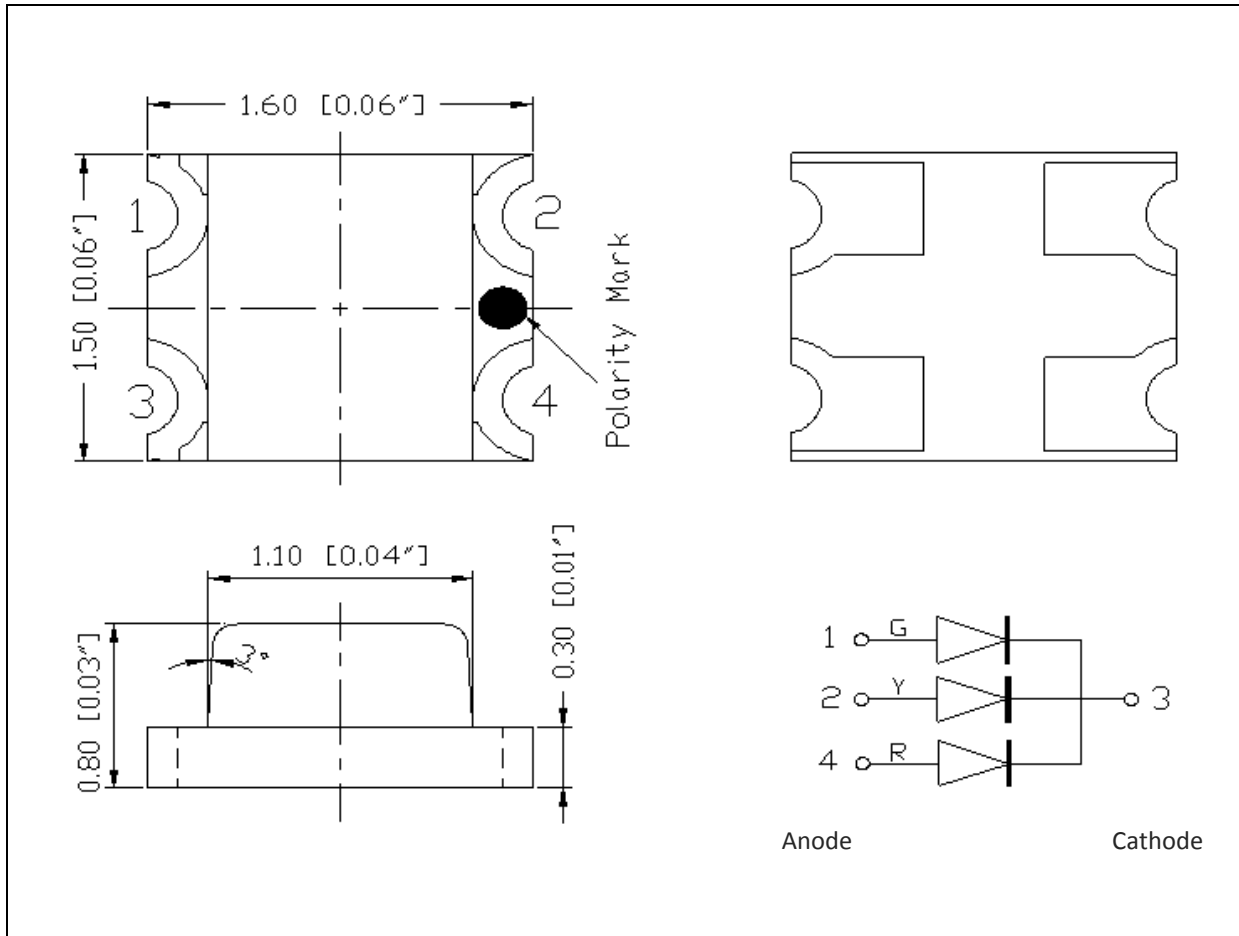
Electrical & Optical Characteristics (Ta=25°C)

| Parameter | Symbol | Values | | | Unit | Test Condition |
|------------------------------|------------------|--------------|-------------|-------------|------|----------------|
| | | Min. | Typ. | Max. | | |
| Forward Voltage | V_F | 1.7/1.7/1.7* | 2.0/2.0/2.0 | 2.5/2.5/2.5 | V | $I_F=20$ mA |
| Luminous Intensity | I_V | 40/80/5 | 60/150/12 | 100/250/25 | mcd | $I_F=20$ mA |
| Dominant Wavelength | λ_D | 630/585/565 | 640/590/570 | 650/595/576 | nm | $I_F=20$ mA |
| Peak Wavelength | λ_P | --- | 650/595/565 | --- | nm | $I_F=20$ mA |
| Spectral Line Half Bandwidth | $\Delta \lambda$ | --- | 18/17/30 | --- | nm | $I_F=20$ mA |
| Viewing Angle | $2\theta_{1/2}$ | --- | 140/140/140 | --- | deg | $I_F=20$ mA |

- * In the order of Red/Yellow/Green.
- Luminous intensity (I_V) $\pm 15\%$, Forward Voltage (V_F) ± 0.1 V, Viewing angle($2\theta_{1/2}$) $\pm 5\%$.
- IS standard testing.

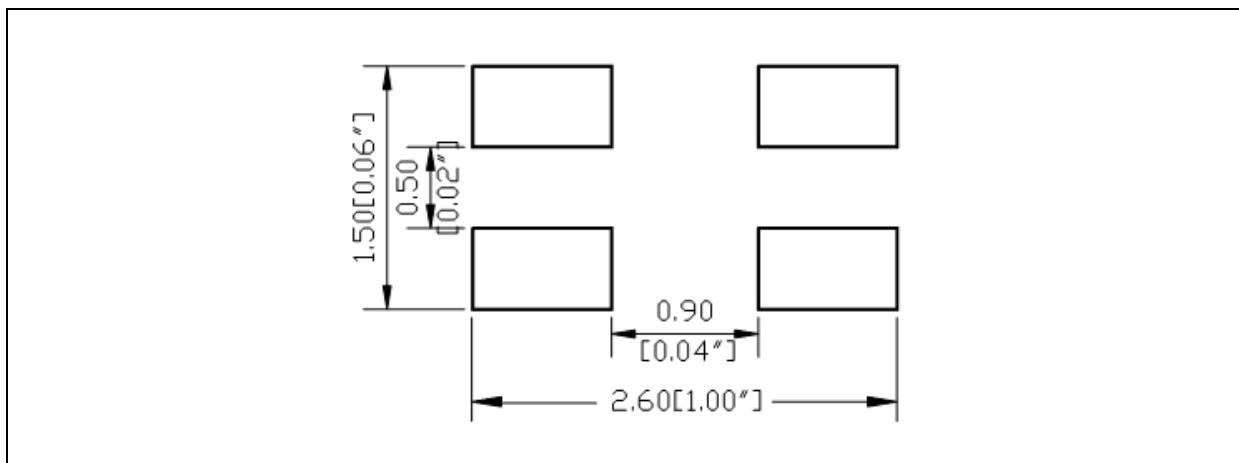
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA}$):

| | Code | Min. | Max. | Unit |
|--------|------|------|------|------|
| Red | B | 1.7 | 2.5 | V |
| Yellow | B | 1.7 | 2.5 | V |
| Green | B | 1.7 | 2.5 | V |

 Luminous Intensity Classifications ($I_F = 20\text{mA}$):

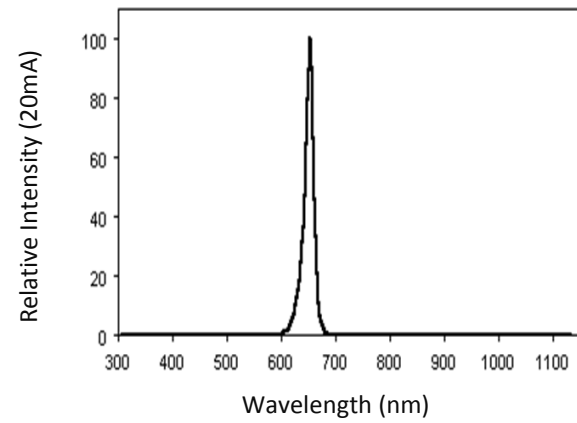
| | Code | Min. | Max. | Unit |
|--------|------|------|------|------|
| Red | F | 40 | 50 | mcd |
| | G | 50 | 63 | |
| | H | 63 | 80 | |
| | I | 80 | 100 | |
| Yellow | I | 80 | 100 | mcd |
| | J | 100 | 125 | |
| | K | 125 | 160 | |
| | L | 160 | 200 | |
| | M | 200 | 250 | |
| Green | Z8 | 5 | 8 | mcd |
| | Z9 | 8 | 12.5 | |
| | A | 12.5 | 16 | |
| | B | 16 | 20 | |
| | C | 20 | 25 | |

Wavelength Classifications ($I_F = 20\text{mA}$):

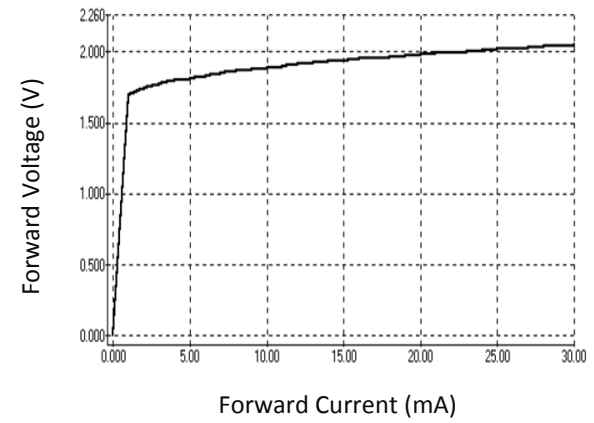
| | Code | Min. | Max. | Unit |
|--------|------|------|------|------|
| Red | V | 630 | 635 | nm |
| | W | 635 | 650 | |
| Yellow | M | 585 | 590 | nm |
| | N | 590 | 595 | |
| Green | H | 565 | 568 | nm |
| | I | 568 | 572 | |
| | J | 572 | 576 | |

ELECTRO-OPTICAL CHARACTERISTICS (RED):

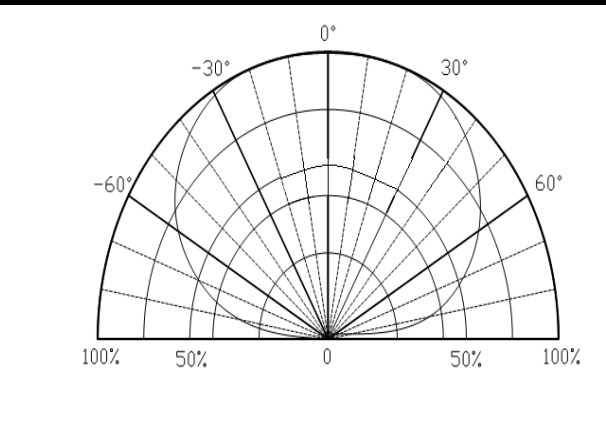
Relative Spectral Distribution



Forward Current v.s. Forward Voltage

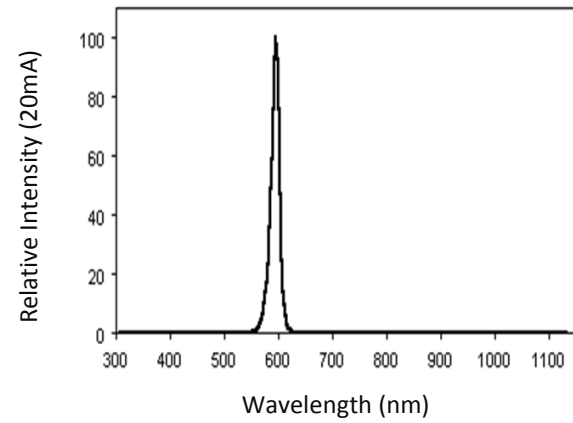


Directive Radiation

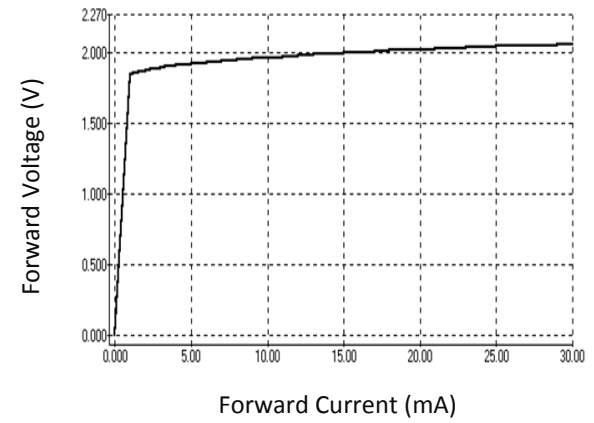


ELECTRO-OPTICAL CHARACTERISTICS (YELLOW):

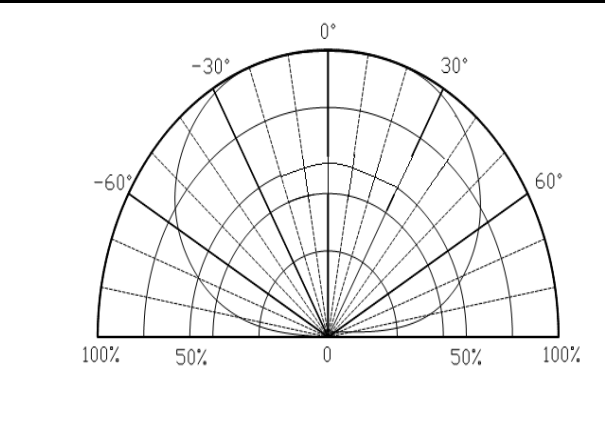
Relative Spectral Distribution



Forward Current v.s. Forward Voltage

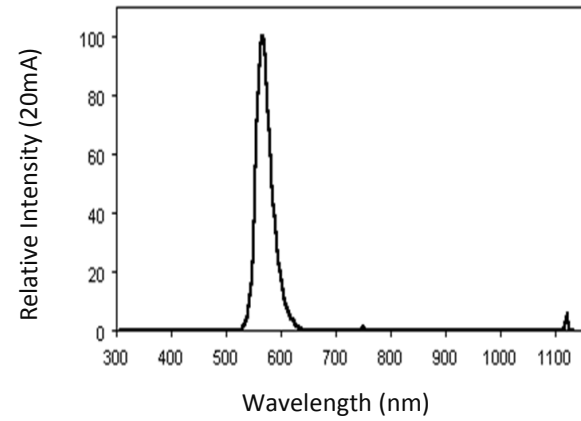


Directive Radiation

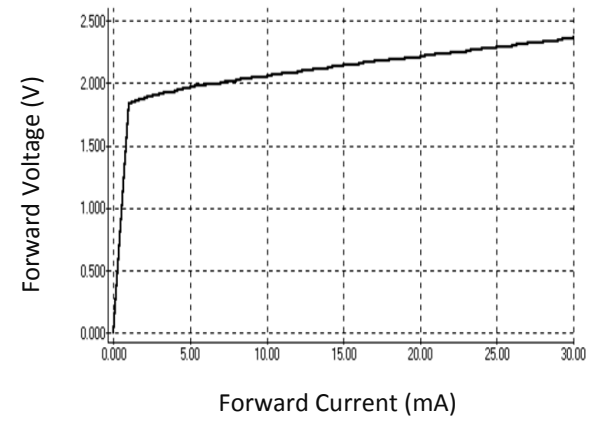


ELECTRO-OPTICAL CHARACTERISTICS (GREEN):

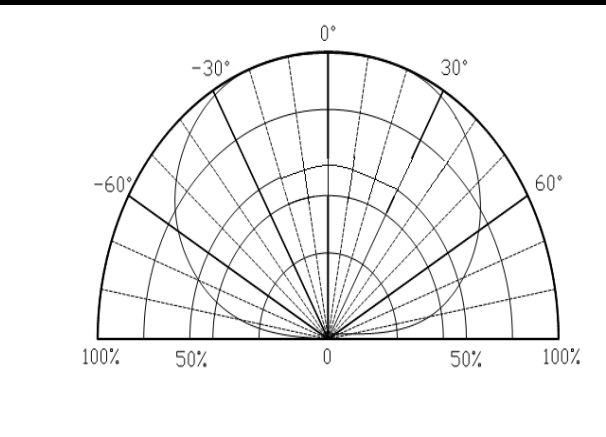
Relative Spectral Distribution



Forward Current v.s. Forward Voltage

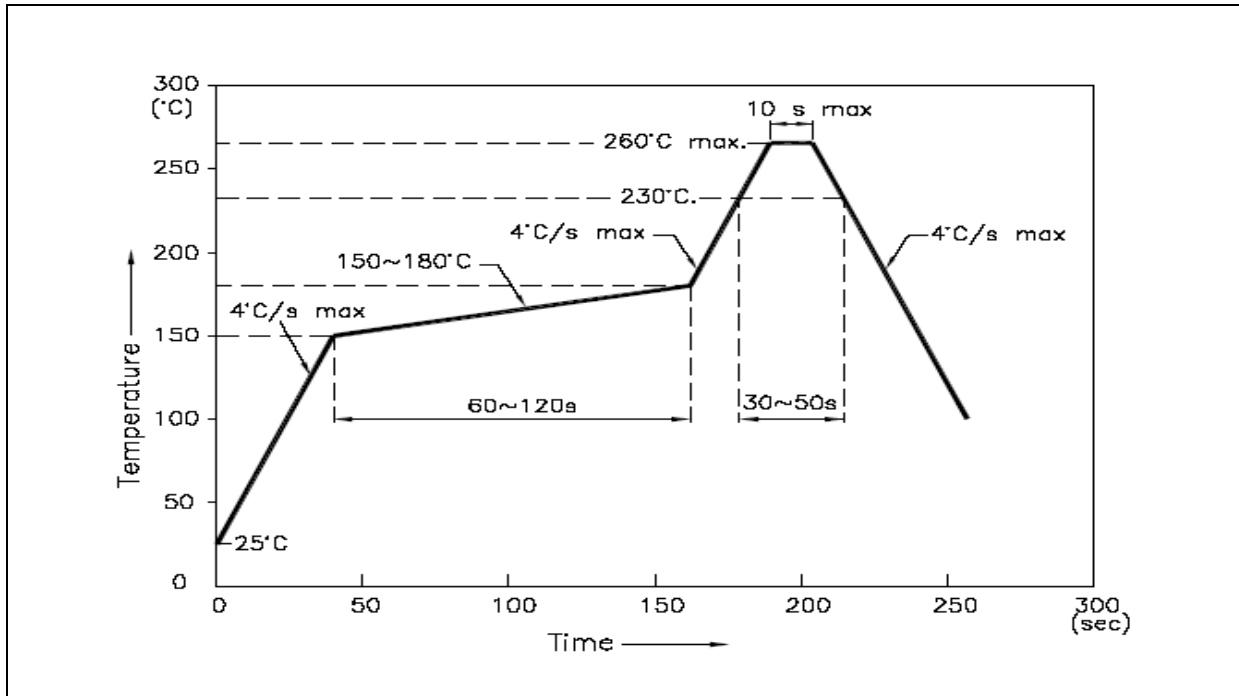


Directive Radiation



RECOMMENDED SOLDERING PROFILE:

Reflow Solder:

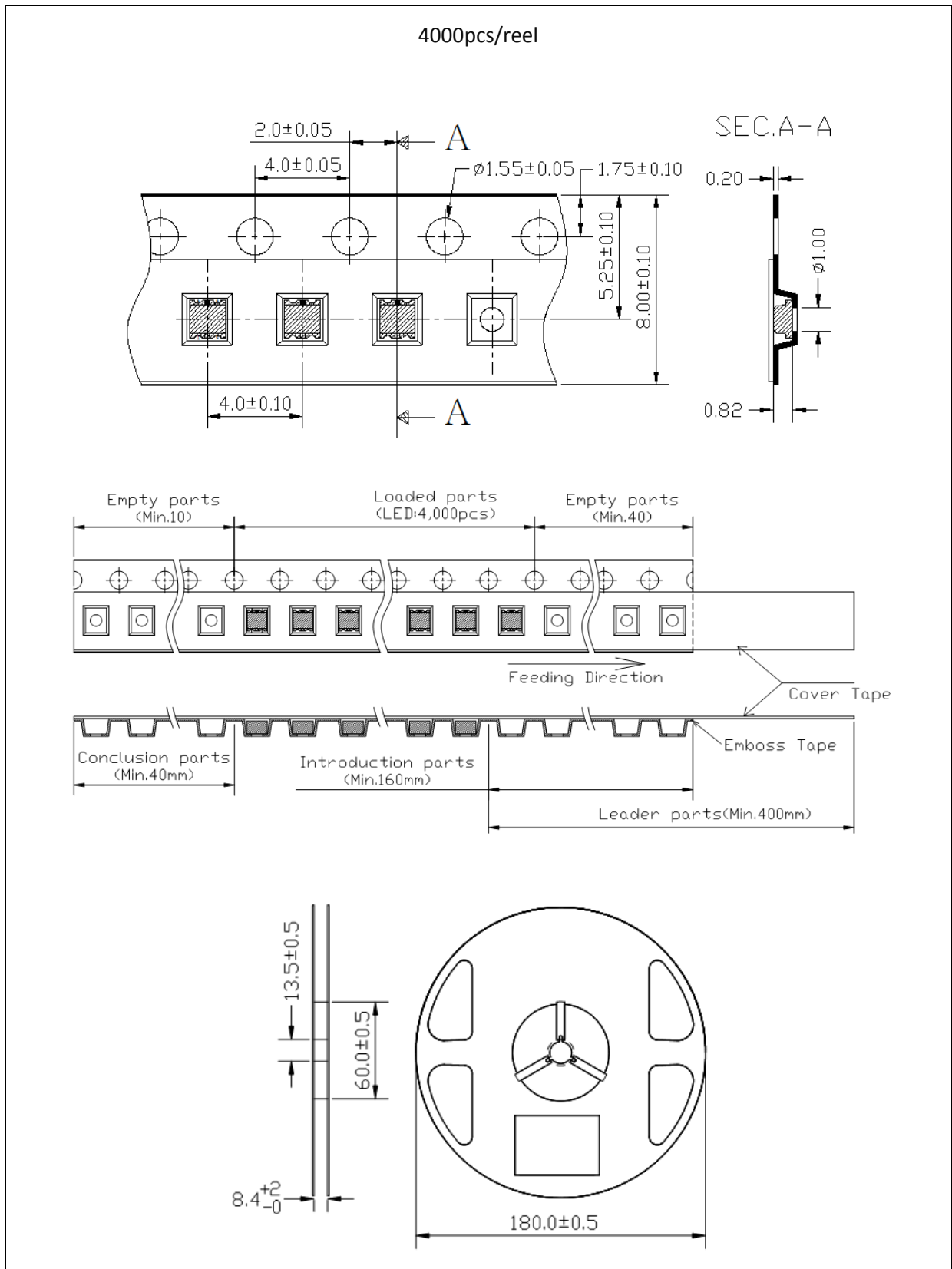


Note:

1. Recommend reflow temperature 245°C.
2. Maximum reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

Baking:

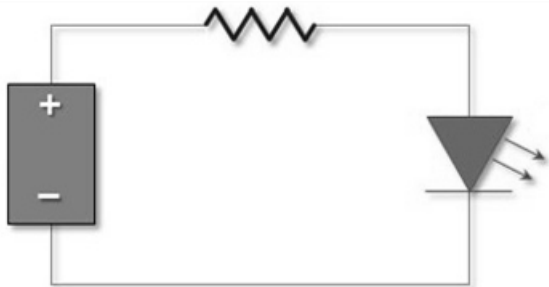
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs.

The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light Blue) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

| Version | Date | Summary of Revision |
|---------|------------|---------------------|
| A1.0 | 07/08/2014 | Datasheet set-up. |